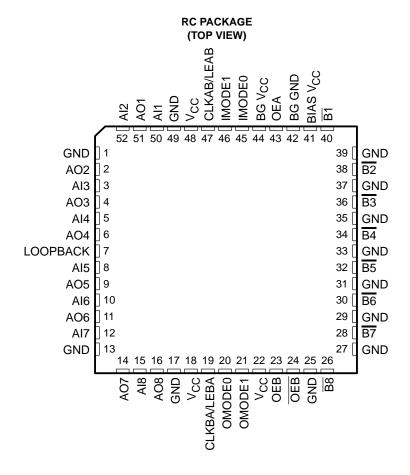
- Compatible With IEEE Std 1194.1-1991 (BTL)
- TTL A Port, Backplane Transceiver Logic (BTL) B Port
- Open-Collector B-Port Outputs Sink 100 mA
- BIAS V<sub>CC</sub> Pin Minimizes Signal Distortion During Live Insertion or Withdrawal
- High-Impedance State During Power Up and Power Down
- B-Port Biasing Network Preconditions the Connector and PC Trace to the BTL High-Level Voltage
- TTL-Input Structures Incorporate Active Clamping Networks to Aid in Line Termination



### description

The SN74FB2033A is an 8-bit transceiver featuring a split input (AI) and output (AO) bus on the TTL-level A port. The common-I/O, open-collector  $\overline{B}$  port operates at backplane transceiver logic (BTL) signal levels.

The logic element for data flow in each direction is configured by two mode inputs (IMODE1 and IMODE0 for B-to-A, OMODE1 and OMODE0 for A-to-B) as a buffer, a D-type flip-flop, or a D-type latch. When configured in the buffer mode, the inverted input data appears at the output port. In the flip-flop mode, data is stored on the rising edge of the appropriate clock input (CLKAB/LEAB or CLKBA/LEBA). In the latch mode, the clock inputs serve as active-high transparent latch enables.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## SN74FB2033A 8-BIT TTL/BTL REGISTERED TRANSCEIVER

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## description (continued)

Data flow in the B-to-A direction, regardless of the logic element selected, is further controlled by the LOOPBACK input. When LOOPBACK is low, B-port data is the B-to-A input. When LOOPBACK is high, the output of the selected A-to-B logic element (prior to inversion) is the B-to-A input.

The AO port-enable/-disable control is provided by OEA. When OEA is low or when V<sub>CC</sub> is less than 2.5 V, the AO port is in the high-impedance state. When OEA is high, the AO port is active (high or low logic levels).

The  $\overline{B}$  port is controlled by OEB and  $\overline{OEB}$ . If OEB is low,  $\overline{OEB}$  is high, or  $V_{CC}$  is less than 2.5 V, the  $\overline{B}$  port is inactive. If OEB is high and  $\overline{OEB}$  is low, the  $\overline{B}$  port is active.

BG V<sub>CC</sub> and BG GND are the bias-generator reference inputs.

The A-to-B and B-to-A logic elements are active, regardless of the state of their associated outputs. The logic elements can enter new data (in flip-flop and latch modes) or retain previously stored data while the associated outputs are in the high-impedance (AO port) or inactive ( $\overline{B}$  port) states.

Output clamps are provided on the BTL outputs to reduce switching noise. One clamp reduces inductive ringing effects on  $V_{OH}$  during a low-to-high transition. The other clamps out ringing below the BTL  $V_{OL}$  voltage of 0.75 V. Both clamps are active only during ac switching and do not affect the BTL outputs during steady-state conditions.

BIAS  $V_{CC}$  establishes a voltage between 1.62 V and 2.1 V on the BTL outputs when  $V_{CC}$  is not connected.

#### ORDERING INFORMATION

TA	PACKAGET		•	TOP-SIDE MARKING	
0°C to 70°C	QFP – RC	Tube	SN74FB2033ARC	FB2033A	

<sup>†</sup>Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



## **Function Tables**

## FUNCTION/MODE

				INPUTS				FUNCTION/MODE
OEA	OEB	OEB	OMODE1	OMODE0	IMODE1	IMODE0	LOOPBACK	FUNCTION/MODE
L	L	Х	Х	Х	Х	Х	X	Isolation
L	Χ	Н	Χ	Χ	Χ	Χ	X	isolation
Х	Н	L	L	L	Χ	Χ	X	Al to B, buffer mode
Х	Н	L	L	Н	Χ	Χ	Х	Al to B, flip-flop mode
Х	Н	L	Н	Х	Х	Х	Х	Al to B, latch mode
Н	L	Х	Х	Х	L	L	L	<del>-</del>
Н	Χ	Н	Χ	Χ	L	L	L	B to AO, buffer mode
Н	L	Χ	Х	Х	L	Н	L	<u> </u>
Н	Χ	Н	Χ	Χ	L	Н	L	B to AO, flip-flop mode
Н	L	Χ	Х	Х	Н	Х	L	5. 101.1
Н	Χ	Н	Χ	Χ	Н	Χ	L	B to AO, latch mode
Н	L	Χ	Х	Х	L	L	Н	Alto AO buffor mode
Н	Χ	Н	Χ	Χ	L	L	Н	Al to AO, buffer mode
Н	L	Х	Х	Х	L	Н	Н	Alto AO flip flop mode
Н	X	Н	Χ	Χ	L	Н	Н	Al to AO, flip-flop mode
Н	L	Х	Х	Х	Н	Х	Н	Al to AO lotab made
Н	Χ	Н	Χ	Χ	Н	X	Н	AI to AO, latch mode
Н	Н	L	Χ	Х	Χ	Χ	L	Al to $\overline{B}$ , $\overline{B}$ to AO

### **ENABLE/DISABLE**

	INPUTS			UTPUTS
OEA	OEA OEB OEB			B
L	Χ	Χ	Hi Z	
Н	Χ	Χ	Active	
X	L	L		Inactive (H)
X	L	Н		Inactive (H)
X	Н	L		Active
X	Н	Н		Inactive (H)

#### **BUFFER**

INPUT	OUTPUT
L	Н
Н	L

#### LATCH

INPU	OUTPUT	
CLK/LE	OUTFUT	
Н	L	Н
Н	Н	L
L	Х	$Q_0$



## **Function Tables (Continued)**

## LOOPBACK

LOOPBACK	Q†
L	B port
Н	Point P‡

<sup>†</sup>Q is the input to the B-to-A logic element.

#### **SELECT**

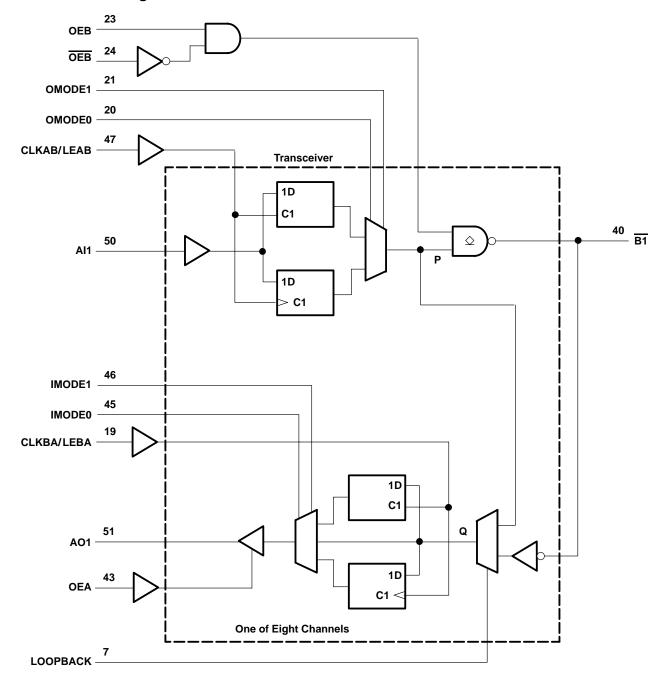
INP	UTS	SELECTED LOGIC
MODE1 MODE0		ELEMENT
L	L	Buffer
L	Н	Flip-flop
Н	Χ	Latch

### FLIP-FLOP

INPU <sup>*</sup>	OUTPUT			
CLK/LE	001701			
L	Х	Q <sub>0</sub>		
1	L	Н		
<b>↑</b>	Н	L		

<sup>‡</sup> P is the output of the A-to-B logic element (see functional block diagram).

## functional block diagram



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input clamp current range, V <sub>I</sub> : Except B port	1.2 V to 7 V
B port	–1.2 V to 3.5 V
Voltage range applied to any $\overline{B}$ output in the disabled or power-off state, $V_0$	–0.5 V to 3.5 V
Voltage range applied to any output in the high state, V <sub>O</sub> : A port	0.5 V to V <sub>CC</sub>
Input clamp current, I <sub>IK</sub> : Except B port	–40 mA
$\overline{B}$ port	–18 mA
Current applied to any single output in the low state, IO: A port	48 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1)	44°C/W
Storage temperature range, T <sub>stg</sub>	. −65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 2)

				MIN	NOM	MAX	UNIT	
V <sub>CC</sub> , BG V <sub>CC</sub>	Supply voltage		4.75	5	5.25	V		
BIAS V <sub>CC</sub>	Supply voltage			4.5	5	5.5	V	
V	High-level input voltage		B port	1.62		2.3	V	
VIH	Tilgit level iliput voltage	Except B port	2			v I		
V	Low-level input voltage		B port	0.75		1.47	٧	
VIL	Low-level input voltage		Except B port			8.0	V	
ЮН	High-level output current		AO port			-3	mA	
1	Lavidaval avitavit avimont		AO port			24	A	
lOL	Low-level output current		B port			100	mA	
Δt/Δν	Input transition rise or fall rate		Except B port			10	ns/V	
TA	Operating free-air temperature			0		70	°C	

NOTE 2: To ensure proper device operation, all unused inputs must be terminated as follows: A and control inputs to V<sub>CC</sub>(5 V) or GND, and B inputs to GND only. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	TEST CONDITIONS			MAX	UNIT	
۷ıĸ		V <sub>CC</sub> = 4.75 V,	I <sub>I</sub> = -18 mA			-1.2	V	
		V <sub>CC</sub> = 4.75 V to 5.25 V,	I <sub>OH</sub> = -10 μA			V <sub>CC</sub> -1.1		
Vон	AO port	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	IOH = -3  mA	2.5	2.85	3.4	V	
		V <sub>CC</sub> = 4.75 V	$I_{OH} = -32 \text{ mA}$	2				
	AO port	V <sub>CC</sub> = 4.75 V	I <sub>OL</sub> = 20 mA		0.33	0.5		
VOL	AO port	VCC = 4.73 V	$I_{OL} = 55 \text{ mA}$			0.8	V	
VOL	<u></u>	V <sub>CC</sub> = 4.75 V	I <sub>OL</sub> = 100 mA	0.75		1.1	V	
	B port	VCC = 4.75 V	$I_{OL} = 4 \text{ mA}$	0.5	-1.2 V VCC-1.1  .5 2.85 3.4 V  2 0.33 0.5 0.8 75 1.1 .5 100   100 -50 -100 100   -50 -100 100   -50 -50 -50 -50 -50 -50 -50 -50 -50 -5			
IĮ	Except B port	$V_{CC} = 0$ ,	V <sub>I</sub> = 5.25 V			100	μΑ	
1	Except B port	V <sub>CC</sub> = 5.25 V,	V <sub>I</sub> = 2.7 V			50	^	
ΉΗ	B port‡	$V_{CC} = 0 \text{ to } 5.25 \text{ V},$	V <sub>I</sub> = 2.1 V			100	μΑ	
IIL	Except B port	V <sub>CC</sub> = 5.25 V	V <sub>I</sub> = 0.5 V			<b>–</b> 50	μΑ	
'IL	B port <sup>‡</sup>	VCC = 3.23 V	V <sub>I</sub> = 0.75 V			-100		
ЮН	B port	$V_{CC} = 0 \text{ to } 5.25 \text{ V},$	V <sub>O</sub> = 2.1 V			100	μΑ	
lozpu		$V_{CC} = 0 \text{ to } 2.1 \text{ V},$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			50	μΑ	
lozpd		$V_{CC} = 2.1 \text{ V to } 0,$	$V_0 = 0.5 \text{ V to } 2.7 \text{ V}$			<b>–</b> 50	μΑ	
lozh	AO port	$V_{CC} = 5.25 \text{ V},$	$V_0 = 2.7 \text{ V}$			50	μΑ	
lozL	AO port	$V_{CC} = 5.25 \text{ V},$	$V_0 = 0.5 V$			<b>–</b> 50	μΑ	
los§	AO port	V <sub>CC</sub> = 5.25 V,	V <sub>O</sub> = 0	-40	-80	-150	mA	
Icc	All outputs on	V <sub>CC</sub> = 5.25 V,	IO = 0		45	70	mA	
Ci	Al port and control inputs	V <sub>I</sub> = 0.5 V or 2.5 V			5		pF	
Co	AO port	V <sub>O</sub> = 0.5 V or 2.5 V			5		pF	
C	B port	$V_{CC} = 0 \text{ to } 4.75 \text{ V}$				6	nE.	
C <sub>io</sub>	per IEEE Std 1194.1-1991	V <sub>CC</sub> = 4.75 V to 5.25 V				6	ρı	

## live-insertion characteristics over recommended operating free-air temperature range (see Note 3)

PAR	RAMETER		TEST CONDIT	MIN	MAX	UNIT	
ICC (BIAS VCC)		$V_{CC} = 0 \text{ to } 4.5 \text{ V}$	V <sub>B</sub> = 0 to 2 V, V <sub>I</sub> (BIAS V <sub>CC</sub> ) = 4.5 V to 5.5 V			10	μA
1CC (B		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	VB = 0 t0 2 v,	V  (BIAS V(C) = 4.5 V to 5.5 V		10	μΑ
VO	B port	$V_{CC} = 0$ ,	V <sub>I</sub> (BIAS V <sub>CC</sub> ) = 4.5 V to 5.5 V			2.1	V
		$V_{CC} = 0$ ,	V <sub>B</sub> = 1 V,	$V_I$ (BIAS $V_{CC}$ ) = 4.5 V to 5.5 V	-1		
lo	B port	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	OEB = 0 to 0.8 V			100	μΑ
		$V_{CC} = 0 \text{ to } 2.2 \text{ V},$	OEB = 0 to 5 V			100	

NOTE 3: The power-up sequence is GND, BIAS  $V_{CC}$ ,  $V_{CC}$ .



<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V. ‡ For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current. § Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

## SN74FB2033A 8-BIT TTL/BTL REGISTERED TRANSCEIVER

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# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

			V <sub>CC</sub> =	= 5 V, 25°C	MIN	MAX	UNIT
			MIN	MAX			
fclock	Clock frequency			150		150	MHz
t <sub>W</sub>	Pulse duration	CLKAB/LEAB or CLKBA/LEBA	3.3		3.3		ns
t <sub>su</sub>	Setup time	Data before CLKAB/LEAB or CLKBA/LEBA↑	2.7		2.7		ns
t <sub>h</sub>	Hold time	Data after CLKAB/LEAB or CLKBA/LEBA↑	0.7		0.7		ns



# switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>0</sub>	CC = 5 \ A = 25°C	/, :	MIN MAX	MAX	UNIT
	(INFO1)	(001F01)	MIN	TYP	MAX			
f <sub>max</sub>			150			150		MHz
<sup>t</sup> PLH	Al	=	2.3	3.6	4.6	2.3	5.6	
<sup>t</sup> PHL	(through mode)	B	1.9	3	4.2	1.9	4.5	ns
<sup>t</sup> PLH	B	AO	2.5	4.2	5.5	2.5	6.1	
<sup>t</sup> PHL	(through mode)	AU	3	4.2	5.6	3	5.7	ns
<sup>t</sup> PLH	Al	=	2.3	3.6	4.6	2.3	5.6	
<sup>t</sup> PHL	(transparent)	B	1.9	3	4.1	1.9	4.5	ns
<sup>t</sup> PLH	B	4.0	2.5	4.2	5.5	2.5	6.1	
<sup>t</sup> PHL	(transparent)	AO	3	4.2	5.6	3	5.7	ns
t <sub>PLH</sub>	0.55	=	2.4	3.7	4.7	2.4	5.8	
<sup>t</sup> PHL	OEB	B	1.8	3	4.1	1.8	4.4	ns
<sup>t</sup> PLH		ı	2	3.4	4.3	2	5.2	
t <sub>PHL</sub>	OEB	B	2	3.3	4.4	2	4.8	ns
<sup>t</sup> PZH	054	10	2	3.5	4.6	2	5.1	ns
<sup>t</sup> PZL	OEA	AO	2.7	4.2	5.1	2.7	5.4	
<sup>t</sup> PHZ	054	4.0	2.1	4	5	2.1	5.5	
t <sub>PLZ</sub>	OEA	AO	1.6	2.8	3.9	1.6	4.3	ns
<sup>t</sup> PLH	CLKAD# FAD	=	3	4.7	5.8	3	6.9	
<sup>t</sup> PHL	CLKAB/LEAB	B	2.8	4.3	5.6	2.8	6.1	ns
<sup>t</sup> PLH	CLKDA/LEDA	PA AO	2	3.6	4.9	2	5.4	ns
<sup>t</sup> PHL	CLKBA/LEBA	AO	2.2	3.5	4.7	2.2	5.1	
<sup>t</sup> PLH	OMORE	_	2.4	5	6.1	2.4	7.2	
<sup>t</sup> PHL	OMODE	B	2.4	4.5	6	2.4	6.7	ns
<sup>t</sup> PLH	MODE	40	1.8	4	5.3	1.8	5.9	
t <sub>PHL</sub>	IMODE	AO	2.3	4.1	5.2	2.3	5.4	ns
<sup>t</sup> PLH	LOODDACK	40	2.4	5	7	2.4	8	
<sup>t</sup> PHL	LOOPBACK	AO	3.1	4.6	5.7	3.1	5.9	ns
<sup>t</sup> PLH	A.1	40	1.9	3.7	5.5	1.9	6.1	
<sup>t</sup> PHL	Al	AO	2.6	4.2	5.6	2.6	5.8	ns
t <sub>r</sub>	Rise time,1.3 V to 1.8 V, B po	ort	0.5	1.2	2.1	0.5	3	-
t <sub>f</sub>	Fall time, 1.8 V to 1.3 V, B po	ort	0.5	1.4	2.3	0.5	3	ns
t <sub>r</sub>	Rise time, 10% to 90%, AO		2	3.3	4.2	2	5	
t <sub>f</sub>	Fall time, 90% to 10%, AO		1	2.5	3.4	1	5	ns
B-port input pulse rejection	-port input pulse rejection							ns

## output-voltage characteristics

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT	
VOHP	Peak output voltage during turnoff of 100 mA into 40 nH	B port	See Figure 1		4.5	V
VOHV	Minimum output voltage during turnoff of 100 mA into 40 nH	B port	See Figure 1	1.62		V
VOLV	Minimum output voltage during high-to-low switch	B port	$I_{OL} = -50 \text{ mA}$	0.3	, and the second	V



## PARAMETER MEASUREMENT INFORMATION

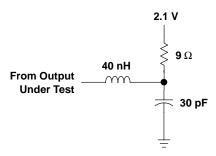
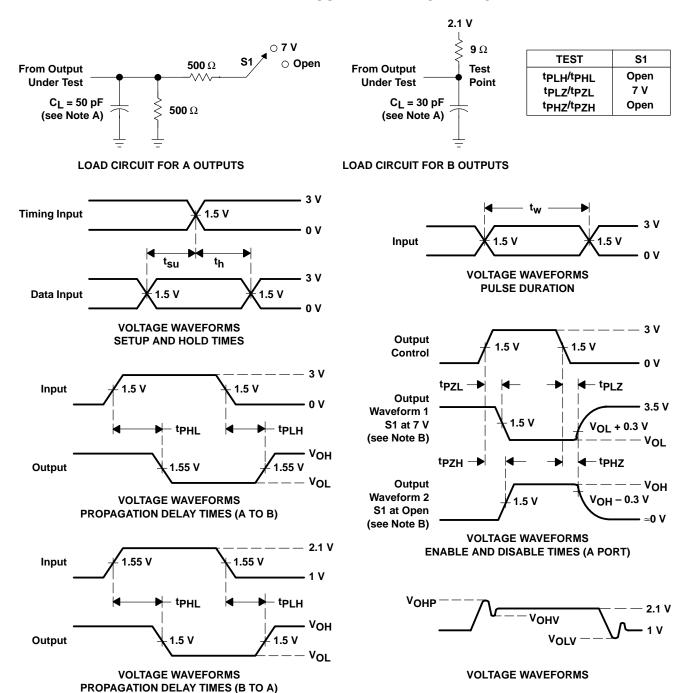


Figure 1. Load Circuit for  $\rm V_{\mbox{OHP}}$  and  $\rm V_{\mbox{OHV}}$ 



#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>I</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: TTL inputs: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_r \leq$  2.5 ns,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
  - D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms







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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins F	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74FB2033ARC	ACTIVE	QFP	RC	52	96	TBD	CU SNPB	Level-2-240C-1 YEAR
SN74FB2033ARCR	ACTIVE	QFP	RC	52	500	TBD	CU SNPB	Level-2-240C-1 YEAR

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74FB2033ARCR	QFP	RC	52	500	330.0	24.4	14.2	14.2	2.6	24.0	24.0	Q2



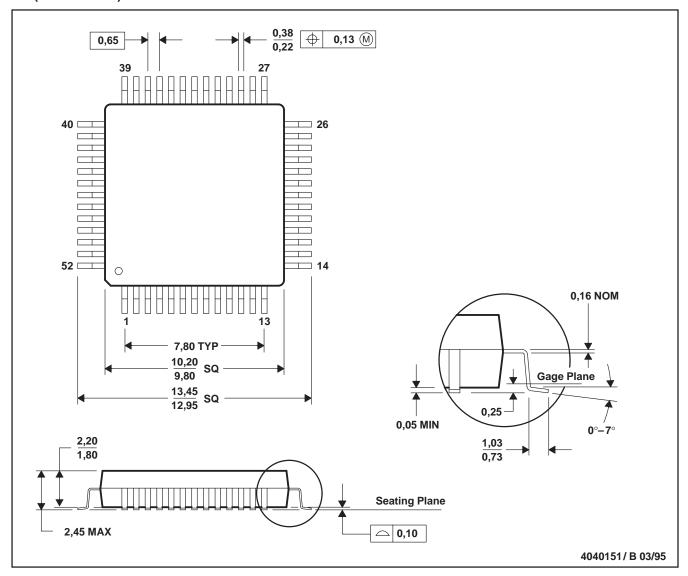


### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74FB2033ARCR	QFP	RC	52	500	346.0	346.0	41.0

## RC (S-PQFP-G52)

## PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-022

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